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I.S. EN 62047-11:2013

Semiconductor devices - Micro-electromechanical devices -- Part 11: Test method for coefficients of linear thermal expansion of free-standing materials for micro-electromechanical systems (IEC 62047-11:2013 (EQV))

## I.S. EN 62047-11:2013

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**Semiconductor devices -  
Micro-electromechanical devices -  
Part 11: Test method for coefficients of linear thermal expansion  
of free-standing materials for micro-electromechanical systems  
(IEC 62047-11:2013)**

Dispositifs à semiconducteurs -  
Dispositifs microélectromécaniques -  
Partie 11: Méthode d'essai pour les  
coefficients de dilatation thermique  
linéaire des matériaux autonomes pour  
systèmes microélectromécaniques  
(CEI 62047-11:2013)

Halbleiterbauelemente -  
Bauelemente der Mikrosystemtechnik -  
Teil 11: Prüfverfahren für lineare  
thermische Ausdehnungskoeffizienten für  
freistehende Werkstoffe der  
Mikrosystemtechnik  
(IEC 62047-11:2013)

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Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Avenue Marnix 17, B - 1000 Brussels**

## **Foreword**

The text of document 47F/154/FDIS, future edition 1 of IEC 62047-11, prepared by IEC/TC 47F "Microelectromechanical systems" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-11:2013.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2014-05-21
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2016-08-21

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-3	-	Semiconductor devices - Micro-electromechanical devices - Part 3: Thin film standard test piece for tensile-testing	EN 62047-3	-

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**SEMICONDUCTOR DEVICES –  
MICRO-ELECTROMECHANICAL DEVICES –**
**Part 11: Test method for coefficients of linear thermal expansion  
of free-standing materials for micro-electromechanical systems**

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International Standard IEC 62047-11 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47F/154/FDIS	47F/161/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62047 series, published under the general title *Semiconductor devices – Micro-electromechanical devices*, can be found on the IEC website.



The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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